

SolidRun Bedrock R8000 Specifications

Feature	Specification	Notes
CPU	AMD Ryzen™ Embedded 8000 Series Ryzen™ Pro 8040 Series 8C/16T Zen4 4nm Up to 5.2 GHz Up to 54W	Ryzen 9 Pro 8945HS Ryzen Embedded 8845HS Ryzen Embedded 8840U
GPU	AMD Radeon™ 780M	Up to 6 WGP/s / 12 CU @ 2800 MHz
NPU	AMD Ryzen™ AI 16 TOPS	
AI Acceleration	Up to 3x Hailo-8 M.2 AI Inferencing Acceleration Module 26 TOPS Up to 2x Hailo-10 M.2 Generative AI Acceleration Module 40 TOPS	2x M.2 key-M 2242 (each precludes an NVME) 1x M.2 key-E 2230 (precludes WiFi)
RAM	128 bit DDR5 5600 up to 96 GB ECC / non-ECC	2x SODIMM (2x32 bit each), conduction cooled
TPM	fTPM 2.0 (in Ryzen) + dTPM 2.0 (Infineon)	Select in BIOS
Display	Up to 4 display outputs HDMI 2.1 DisplayPort 2.1	Max resolution / refresh rate: 7680x4320 @ 60Hz 3840x2160 @ 240Hz
Storage	Up to 3x NVMe PCIe Gen4 x 4	M.2 key-M 2280 Optional power-loss-protection NVMe is conduction cooled Each 2nd/3rd NVMe precludes one Hailo-8 key-M
LAN	Up to 4x 2.5 GbE (Intel I226)	4x RJ45 (NIO R8000 4X25) 2x RJ45 (NIO R7000 Basic)
WLAN	WiFi 6E (Intel AX210) BT 5.3	2x RP-SMA antennas Optional and upgradable (M.2 key-E 2230)
Modem	4G / 5G (Quectel)	2x SMA antennas Optional and upgradable (M.2 key-B 3042 / 3052)
USB	Up to 1x USB 4.0 40 Gb/s 1x USB 3.2 gen 2 10 Gb/s 3x USB 3.2 gen 2 5 Gb/s	Connectors: USB-C / USB-A
Console	Serial over USB	mini-USB connector
BIOS	AMI Aptio V	Dual SPI FLASH for redundancy Console redirection
Operating systems	Windows 10/11/IoT, Linux	Other x86 operating systems supported
Power	Up to 12V-60V DC	Phoenix terminal Other DC connectors available
Temperature range	Up to -40°C to 85°C	Also available in commercial temperature range
Enclosure	All aluminum enclosure, fanless cooling	
Dimensions	30W model: 45 mm (W) x 160 mm (H) x 130 mm (D) - 0.9 liter 60W model: 73 mm (W) x 160 mm (H) x 130 mm (D) - 1.5 liter Tile model: 29 mm (W) x 160 mm (H) x 130 mm (D) - 0.6 liter	
Mounting	DIN-rail, wall, VESA, table top	

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